

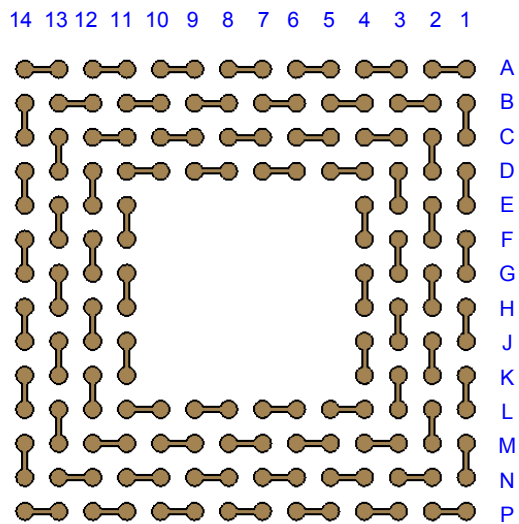
- Notes: (Unless Otherwise Specified).
- 1) ALL DIMENSIONS ARE IN MM.
  - 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
  - 3) BALL DIAMETER (BEFORE REFLOW): 0.508mm [20 MIL].
  - 4) SOLDER MASK DEFINED PAD OPENING: 0.43mm [17 MIL].
  - 5) PAD Cu DIAMETER: 0.508mm [20 MIL].
  - 6) SUBSTRATE MATERIAL: BT RESIN.
  - 7) DUMMY DIE OPTIONAL.
  - 8) DAISY CHAIN PATTERN (SEE PAGE 2).
  - 9) MSL-3 RECOMMEND BAKING 24 HOURS @ 125C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

SECTION A-A

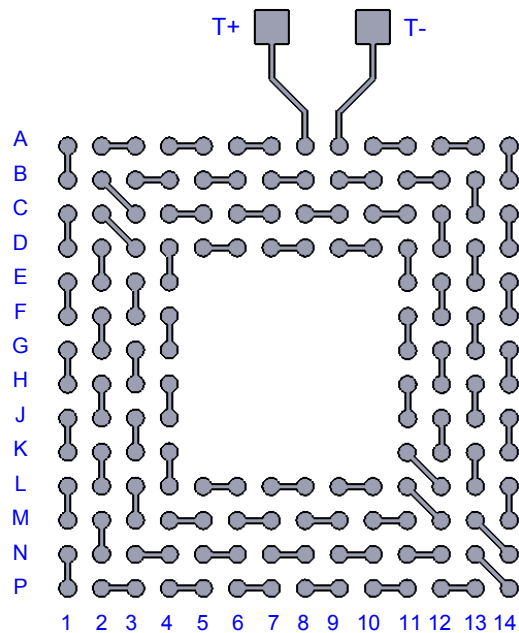
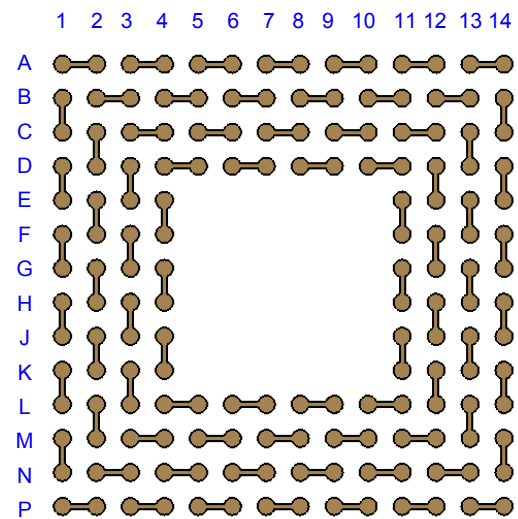
PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	BALL CODE	RoHS	Si DIE
BGA160T1.0C-DC147D	Sn96.5/Ag3.0/Cu0.5	SAC305	YES	YES
BGA160T1.0-DC147D	Sn63/Pb37	Sn63	NO	YES

APPROVALS		DATE				
DRAWN	T. Au	11/01/2012				
ENG	M. Hart	11/01/2012	TITLE		BGA160T1.0-DC147D DAISY CHAIN DUMMY	
MFG			SCALE	SIZE	DRAWING NO.	REV
QA			5.5:1	A	511470	A
CUST			DO NOT SCALE DRAWING		SHEET 1 OF 2	
REVISED						

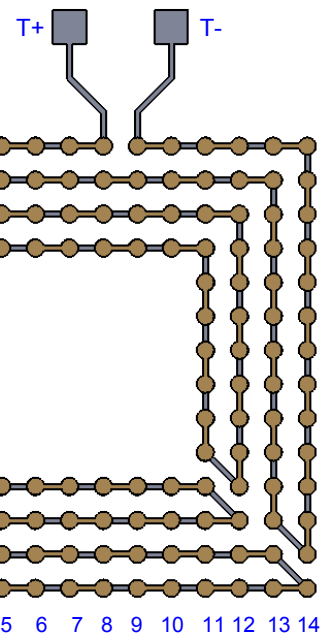
### BALL VIEW



### BOTTOM SIDE (TOP X-RAY VIEW)



TEST VEHICLE BOARD



AFTER MOUNTING

**Notes:**

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.508mm [20 MIL].
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.152mm [6 MIL].
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING 0.43mm [17 MIL].

<b>TopLine</b> ®			
TITLE		BGA160T1.0-DC147D DAISY CHAIN DUMMY	
SCALE	SIZE	DRAWING NO.	REV
4.5:1	A	511470	A
DO NOT SCALE DRAWING			SHEET 2 OF 2